

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

Claims 1-4. (canceled).

5. (currently amended): A semiconductor wafer processing method, comprising adhering a removable pressure-sensitive adhesive sheet which comprises a pressure-sensitive adhesive layer which is made of at least a pressure-sensitive adhesive comprising a-an obtained polymer in which the content of low-molecular components having a molecular weight of 10^5 or lower is 10% by weight or lower, and the obtained polymer has a weight average molecular weight of 930,000 to 2,100,000, to a front or back surface of the wafer, and processing the wafer, wherein the obtained polymer is an acrylic polymer obtained by polymerizing one or more monomers in liquid or supercritical carbon dioxide.